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BGU8007

SiGe:C Low Noise Amplifier MMIC for GPS, GLONASS, Galileo and Compass

Rev. 2 — 30 March 2012

Product data sheet

1. Product profile

1.1 General description

The BGU8007 is a Low Noise Amplifier (LNA) for GNSS receiver applications in a plastic leadless 6-pin, extremely small SOT886 package. The BGU8007 requires only one external matching inductor and one external decoupling capacitor.

The BGU8007 adapts itself to the changing environment resulting from co-habitation of different radio systems in modern cellular handsets. It has been designed for low power consumption and optimal performance when jamming signals from co-existing cellular transmitters are present. At low jamming power levels it delivers 19 dB gain at a noise figure of 0.75 dB. During high jamming power levels, resulting for example from a cellular transmit burst, it temporarily increases its bias current to improve sensitivity.

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Covers full GNSS L1 band, from 1559 MHz to 1610 MHz
- Noise figure (NF) = 0.75 dB
- Excellent low NF < 1 dB in the presence of strong jamming signals
- Gain 19 dB
- High input 1 dB compression point $P_{i(1dB)}$ of -11 dBm
- High out of band $IP3_i$ of 4 dBm
- Supply voltage 1.5 V to 2.5 V
- Power-down mode current consumption < 1 μ A
- Optimized performance at low supply current of 4.6 mA
- Integrated temperature stabilized bias for easy design
- Requires only one input matching inductor and one supply decoupling capacitor
- Input and output DC decoupled
- ESD protection on all pins (HBM > 2 kV)
- Integrated matching for the output
- Small 6-pin leadless package 1 mm \times 1.45 mm \times 0.5 mm
- 110 GHz transit frequency - SiGe:C technology



1.3 Applications

- LNA for GPS, GLONASS, Galileo and Compass (BeiDou) in smart phones, feature phones, tablet PCs, Personal Navigation Devices, Digital Still Cameras, Digital Video Cameras, RF Front End modules, complete GPS chipset modules and theft protection (laptop, ATM)

1.4 Quick reference data

Table 1. Quick reference data

f = 1559 MHz to 1610 MHz; *V*_{CC} = 1.8 V; *P*_i < -40 dBm; *T*_{amb} = 25 °C; input matched to 50 Ω using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<i>V</i> _{CC}	supply voltage	RF input AC coupled	1.5	-	2.5	V
<i>I</i> _{CC}	supply current	<i>V</i> _{ENABLE} ≥ 0.8 V				
		<i>P</i> _i < -40 dBm	3.3	4.6	5.9	mA
		<i>P</i> _i = -20 dBm	8.4	11.9	14.7	mA
<i>G</i> _p	power gain	<i>P</i> _i < -40 dBm, no jammer	17.0	19.0	20.5	dB
		<i>P</i> _i = -20 dBm, no jammer	18.5	20.5	21.5	dB
NF	noise figure	<i>P</i> _i < -40 dBm, no jammer [1]	-	0.75	1.1	dB
		<i>P</i> _i < -40 dBm, no jammer [2]	-	0.80	1.2	dB
		<i>P</i> _i = -20 dBm, no jammer [2]	-	1.0	1.4	dB
<i>P</i> _{i(1dB)}	input power at 1 dB gain compression	<i>f</i> = 1559 MHz to 1610 MHz				
		<i>V</i> _{CC} = 1.5 V	-15	-12	-	dBm
		<i>V</i> _{CC} = 1.8 V	-14	-11	-	dBm
		<i>V</i> _{CC} = 2.2 V	-13	-10	-	dBm
IP3 _i	input third-order intercept point	<i>f</i> = 1.575 GHz				
		<i>V</i> _{CC} = 1.5 V	[3]	1	4	dBm
		<i>V</i> _{CC} = 1.8 V	[3]	1	4	dBm
		<i>V</i> _{CC} = 2.2 V	[3]	2	5	dBm

[1] PCB losses are subtracted.

[2] Including PCB losses.

[3] *f*₁ = 1713 MHz; *f*₂ = 1851 MHz; *P*₁ = *P*₂ = -30 dBm.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	GND	<p>Transparent top view</p>	<p>sym129</p>
2	GND		
3	RF_IN		
4	<i>V</i> _{CC}		
5	ENABLE		
6	RF_OUT		

3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BGU8007	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886

4. Marking

Table 4. Marking codes

Type number	Marking code
BGU8007	UZ

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
V_{CC}	supply voltage	RF input AC coupled	-0.5	+4.0	V	
V_{ENABLE}	voltage on pin ENABLE	$V_{ENABLE} < V_{CC} + 0.6$	[2]	-0.5	+4.0	V
V_{RF_IN}	voltage on pin RF_IN	DC; $V_{RF_IN} < V_{CC} + 0.6$	[2][3]	-0.5	+4.0	V
V_{RF_OUT}	voltage on pin RF_OUT	DC; $V_{RF_OUT} < V_{CC} + 0.6$	[2][3]	-0.5	+4.0	V
P_i	input power		-	0	dBm	
P_{tot}	total power dissipation	$T_{sp} \leq 130$ °C	[1]	55	mW	
T_{stg}	storage temperature		-65	+150	°C	
T_j	junction temperature		-	150	°C	
V_{ESD}	electrostatic discharge voltage	Human Body Model (HBM); According JEDEC standard 22-A114E	-	2	kV	
		Charged Device Model (CDM); According JEDEC standard 22-C101B	-	1	kV	

[1] T_{sp} is the temperature at the soldering point of the emitter lead.

[2] Warning: due to internal ESD diode protection, the applied DC voltage should not exceed $V_{CC} + 0.6$ and shall not exceed 5.0 V in order to avoid excess current.

[3] The RF input and RF output are AC coupled through internal DC blocking capacitors.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		225	K/W

7. Characteristics

Table 7. Characteristics

$f = 1559 \text{ MHz to } 1610 \text{ MHz}$; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \geq 0.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ }^\circ\text{C}$; input matched to $50 \text{ } \Omega$ using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V_{CC}	supply voltage	RF input AC coupled	1.5	-	2.5	V	
I_{CC}	supply current	$V_{ENABLE} \geq 0.8 \text{ V}$					
		$P_i < -40 \text{ dBm}$	3.3	4.6	5.9	mA	
		$P_i = -20 \text{ dBm}$	8.4	11.9	14.7	mA	
		$V_{ENABLE} \leq 0.3 \text{ V}$	-	-	1	μA	
T_{amb}	ambient temperature		-40	+25	+85	$^\circ\text{C}$	
G_p	power gain	$T_{amb} = 25 \text{ }^\circ\text{C}$					
		$P_i < -40 \text{ dBm}$, no jammer	17.0	19.0	20.5	dB	
		$P_i = -20 \text{ dBm}$, no jammer	18.5	20.5	21.5	dB	
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 850 \text{ MHz}$	18.5	20.5	21.5	dB	
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 1850 \text{ MHz}$	18.5	20.5	21.5	dB	
		$-40 \text{ }^\circ\text{C} \leq T_{amb} \leq +85 \text{ }^\circ\text{C}$					
		$P_i < -40 \text{ dBm}$, no jammer	16	-	21	dB	
		$P_i = -20 \text{ dBm}$, no jammer	17	-	22	dB	
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 850 \text{ MHz}$	17	-	22	dB	
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 1850 \text{ MHz}$	17	-	22	dB	
RL_{in}	input return loss	$P_i < -40 \text{ dBm}$	4	5.5	-	dB	
		$P_i = -20 \text{ dBm}$	6	9	-	dB	
RL_{out}	output return loss	$P_i < -40 \text{ dBm}$	15	26	-	dB	
		$P_i = -20 \text{ dBm}$	15	27	-	dB	
ISL	isolation		22	24	-	dB	
NF	noise figure	$T_{amb} = 25 \text{ }^\circ\text{C}$					
		$P_i < -40 \text{ dBm}$, no jammer	[1]	-	0.75	1.1	dB
		$P_i < -40 \text{ dBm}$, no jammer	[2]	-	0.80	1.2	dB
		$P_i = -20 \text{ dBm}$, no jammer	[2]	-	1.0	1.4	dB
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 850 \text{ MHz}$	[2]	-	0.8	1.2	dB
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 1850 \text{ MHz}$	[2]	-	1.1	1.5	dB
		$-40 \text{ }^\circ\text{C} \leq T_{amb} \leq +85 \text{ }^\circ\text{C}$					
		$P_i < -40 \text{ dBm}$, no jammer	[2]	-	-	1.5	dB
		$P_i = -20 \text{ dBm}$, no jammer	[2]	-	-	1.7	dB
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 850 \text{ MHz}$	[2]	-	-	1.5	dB
		$P_{jam} = -20 \text{ dBm}$; $f_{jam} = 1850 \text{ MHz}$	[2]	-	-	1.8	dB

Table 7. Characteristics ...continued

$f = 1559 \text{ MHz to } 1610 \text{ MHz}$; $V_{CC} = 1.8 \text{ V}$; $V_{ENABLE} \geq 0.8 \text{ V}$; $P_i < -40 \text{ dBm}$; $T_{amb} = 25 \text{ }^\circ\text{C}$; input matched to $50 \text{ } \Omega$ using a 5.6 nH inductor; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$P_{i(1dB)}$	input power at 1 dB gain compression	$f = 1559 \text{ MHz to } 1610 \text{ MHz}$					
		$V_{CC} = 1.5 \text{ V}$	-15	-12	-	dBm	
		$V_{CC} = 1.8 \text{ V}$	-14	-11	-	dBm	
		$V_{CC} = 2.2 \text{ V}$	-13	-10	-	dBm	
		$f = 806 \text{ MHz to } 928 \text{ MHz}$					
		$V_{CC} = 1.5 \text{ V}$	[3]	-13	-10	-	dBm
		$V_{CC} = 1.8 \text{ V}$	[3]	-13	-10	-	dBm
		$V_{CC} = 2.2 \text{ V}$	[3]	-12	-9	-	dBm
		$f = 1612 \text{ MHz to } 1909 \text{ MHz}$					
		$V_{CC} = 1.5 \text{ V}$	[3]	-12	-9	-	dBm
		$V_{CC} = 1.8 \text{ V}$	[3]	-11	-8	-	dBm
		$V_{CC} = 2.2 \text{ V}$	[3]	-10	-7	-	dBm
$IP3_i$	input third-order intercept point	$f = 1.575 \text{ GHz}$					
		$V_{CC} = 1.5 \text{ V}$	[4]	1	4	-	dBm
		$V_{CC} = 1.8 \text{ V}$	[4]	1	4	-	dBm
		$V_{CC} = 2.2 \text{ V}$	[4]	2	5	-	dBm
t_{on}	turn-on time		[5]	-	-	2	μs
t_{off}	turn-off time		[5]	-	-	1	μs

- [1] PCB losses are subtracted.
- [2] Including PCB losses.
- [3] Out of band.
- [4] $f_1 = 1713 \text{ MHz}$; $f_2 = 1851 \text{ MHz}$; $P_1 = P_2 = -30 \text{ dBm}$.
- [5] Within 10 % of the final gain.

Table 8. ENABLE (pin 5)

$-40 \text{ }^\circ\text{C} \leq T_{amb} \leq +85 \text{ }^\circ\text{C}$; $1.5 \text{ V} \leq V_{CC} \leq 2.5 \text{ V}$

$V_{ENABLE} \text{ (V)}$	State
≤ 0.3	OFF
≥ 0.8	ON

8. Application information

8.1 GNSS LNA

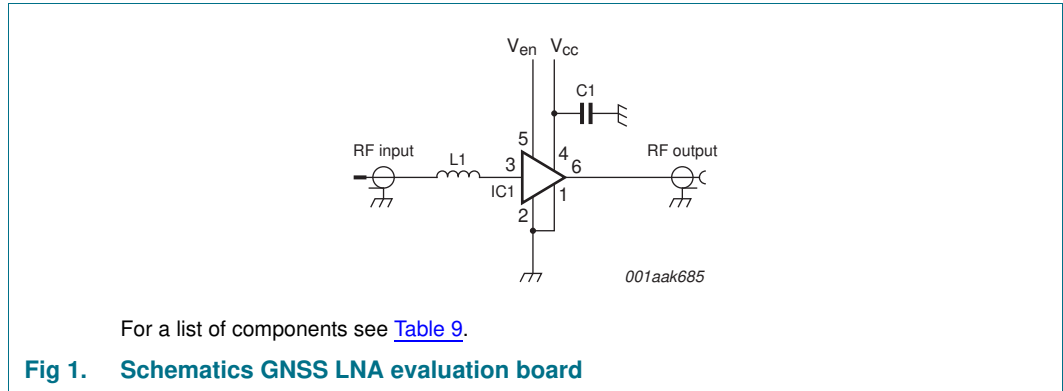
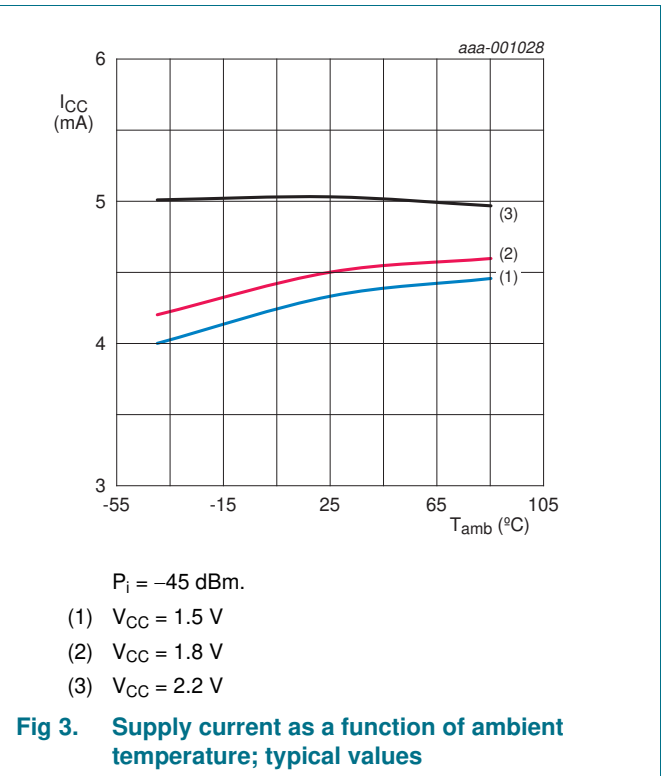
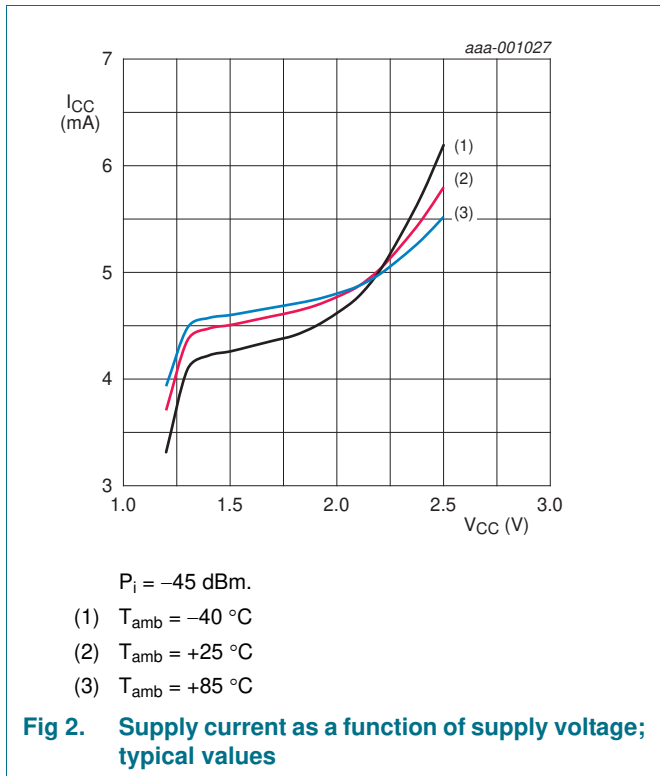
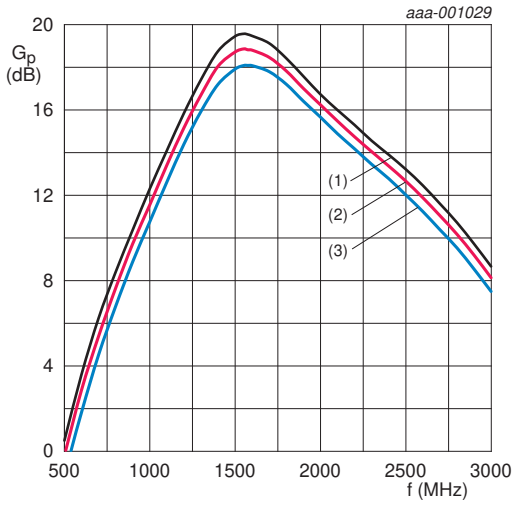


Table 9. List of components

For schematics see [Figure 1](#).

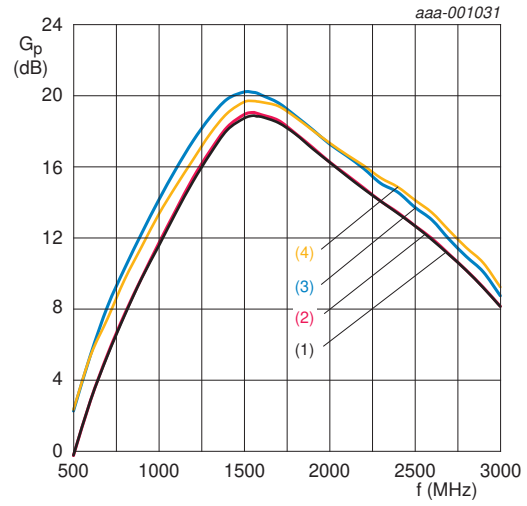
Component	Description	Value	Supplier	Remarks
C1	decoupling capacitor	1 nF	various	
IC1	BGU8007	-	NXP	
L1	high quality matching inductor	5.6 nH	Murata LQW15A	





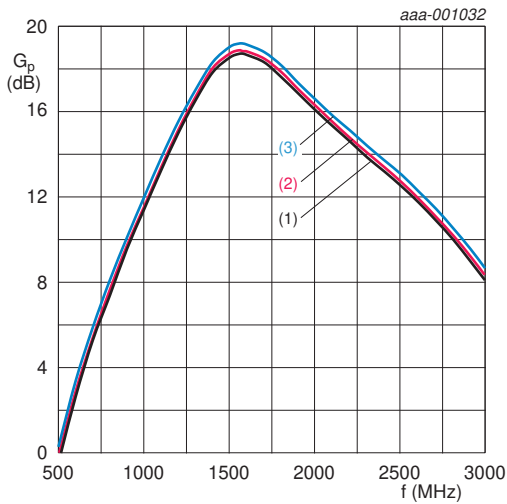
- $V_{CC} = 1.8 \text{ V}; P_i = -45 \text{ dBm}.$
- (1) $T_{amb} = -40 \text{ }^\circ\text{C}$
 - (2) $T_{amb} = +25 \text{ }^\circ\text{C}$
 - (3) $T_{amb} = +85 \text{ }^\circ\text{C}$

Fig 4. Power gain as a function of frequency; typical values



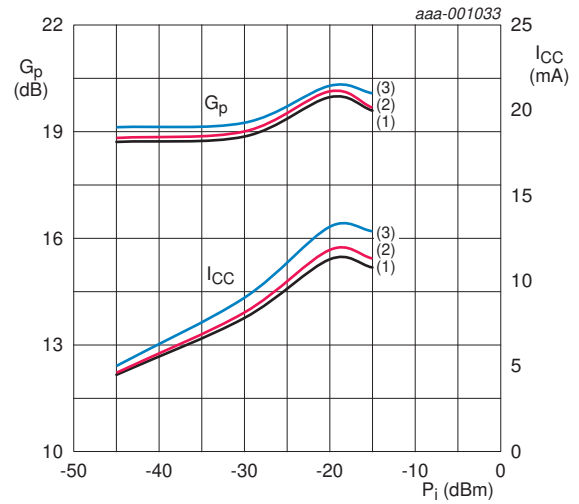
- $V_{CC} = 1.8 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}.$
- (1) $P_i = -45 \text{ dBm}$
 - (2) $P_i = -30 \text{ dBm}$
 - (3) $P_i = -20 \text{ dBm}$
 - (4) $P_i = -15 \text{ dBm}$

Fig 5. Power gain as a function of frequency; typical values



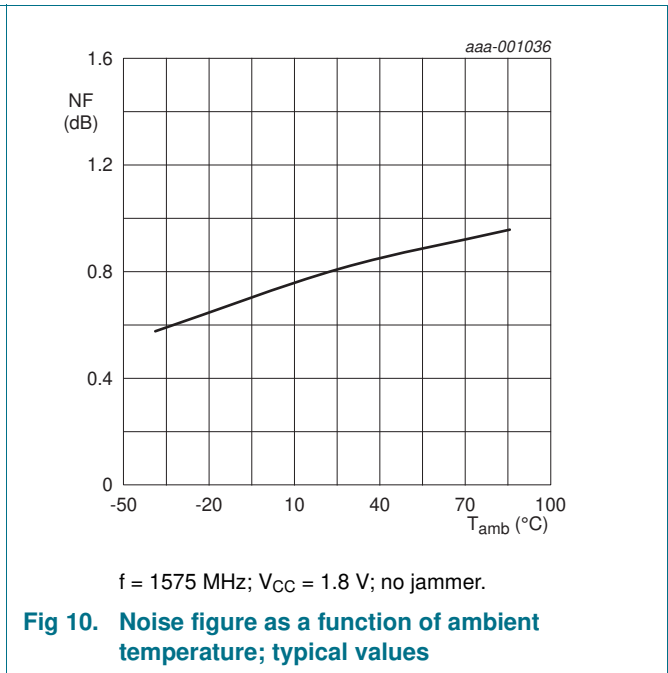
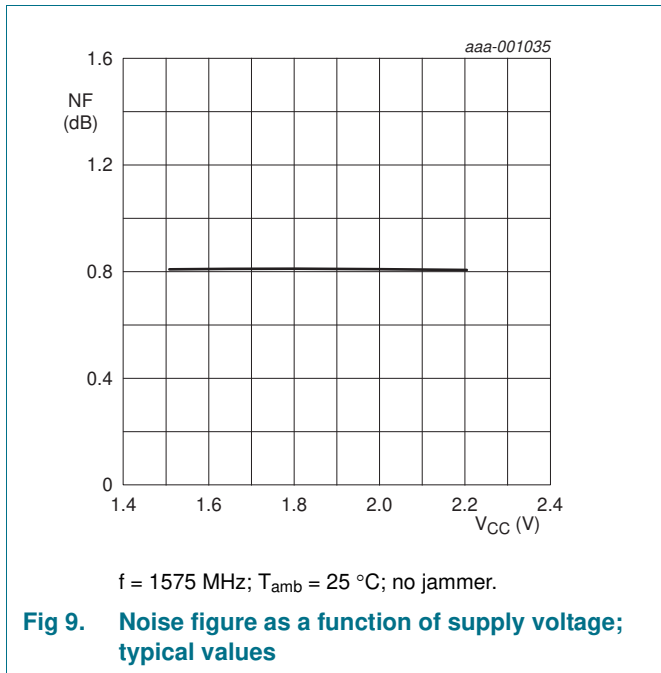
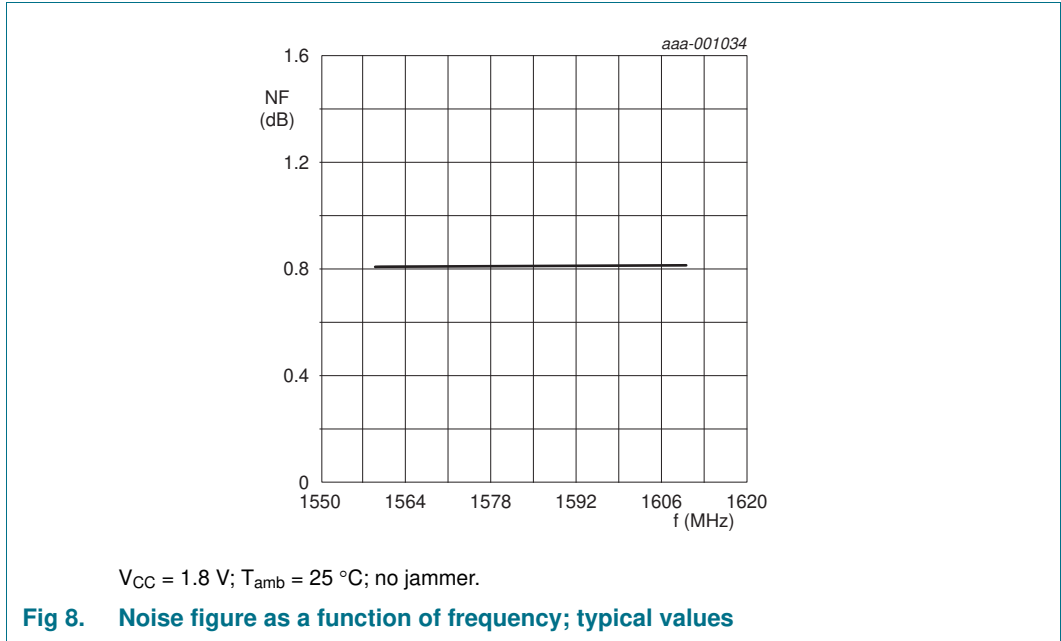
- $P_i = -45 \text{ dBm}; T_{amb} = 25 \text{ }^\circ\text{C}.$
- (1) $V_{CC} = 1.5 \text{ V}$
 - (2) $V_{CC} = 1.8 \text{ V}$
 - (3) $V_{CC} = 2.2 \text{ V}$

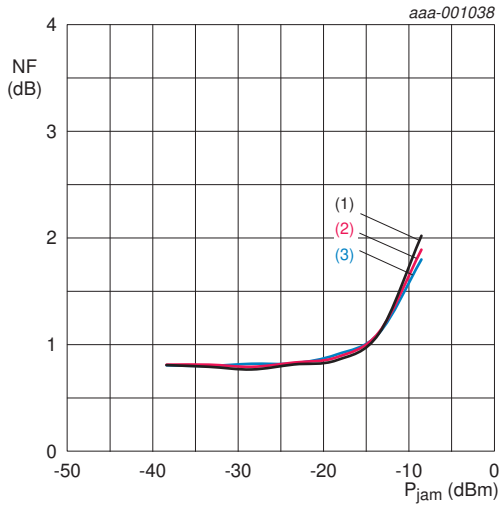
Fig 6. Power gain as a function of frequency; typical values



- $T_{amb} = 25 \text{ }^\circ\text{C}; f = 1575 \text{ MHz}.$
- (1) $V_{CC} = 1.5 \text{ V}$
 - (2) $V_{CC} = 1.8 \text{ V}$
 - (3) $V_{CC} = 2.2 \text{ V}$

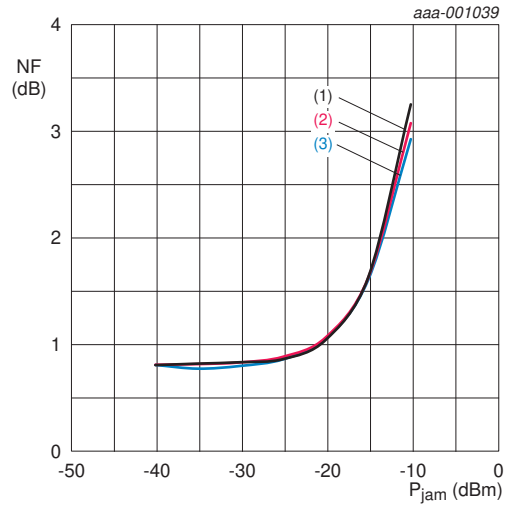
Fig 7. Power gain as a function of input power; typical values





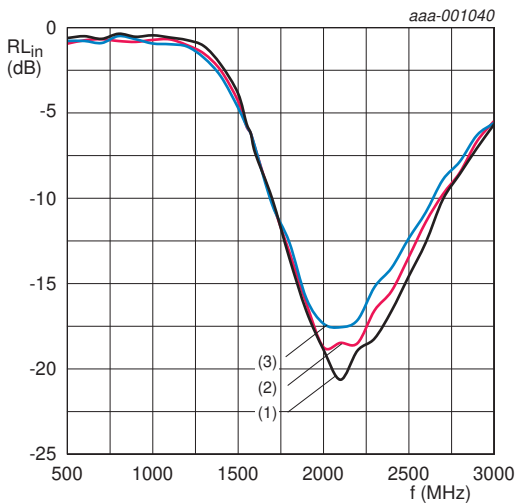
$f_{jam} = 850 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}; f = 1575 \text{ MHz}.$
 (1) $V_{CC} = 1.5 \text{ V}$
 (2) $V_{CC} = 1.8 \text{ V}$
 (3) $V_{CC} = 2.2 \text{ V}$

Fig 11. Noise figure as a function of jamming power; typical values



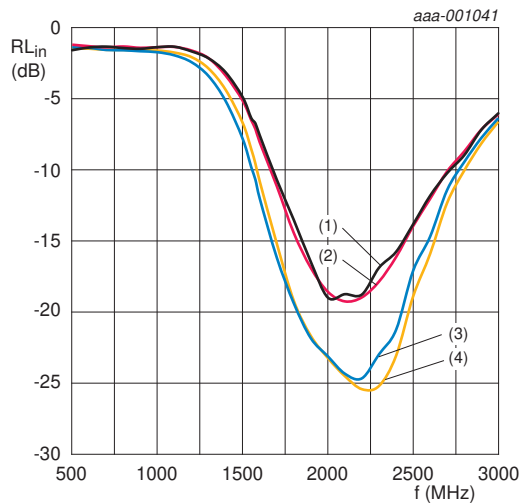
$f_{jam} = 1850 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}; f = 1575 \text{ MHz}.$
 (1) $V_{CC} = 1.5 \text{ V}$
 (2) $V_{CC} = 1.8 \text{ V}$
 (3) $V_{CC} = 2.2 \text{ V}$

Fig 12. Noise figure as a function of jamming power; typical values



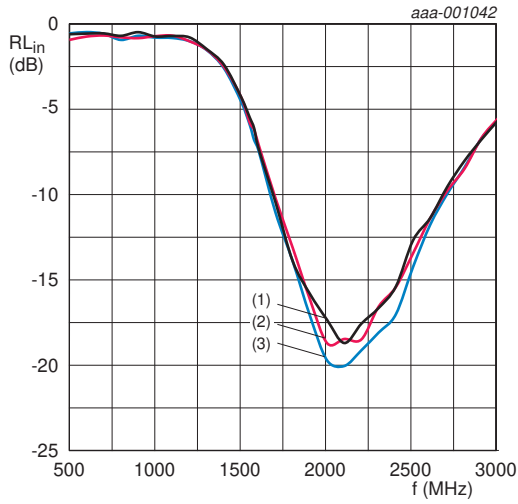
$V_{CC} = 1.8 \text{ V}; P_i = -45 \text{ dBm}.$
 (1) $T_{amb} = -40 \text{ }^\circ\text{C}$
 (2) $T_{amb} = +25 \text{ }^\circ\text{C}$
 (3) $T_{amb} = +85 \text{ }^\circ\text{C}$

Fig 13. Input return loss as a function of frequency; typical values



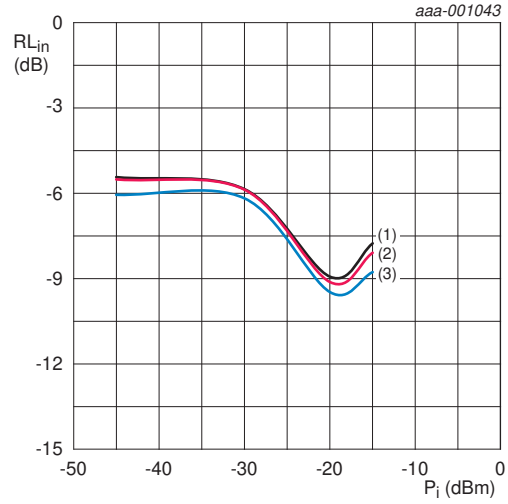
$V_{CC} = 1.8 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}.$
 (1) $P_i = -45 \text{ dBm}$
 (2) $P_i = -30 \text{ dBm}$
 (3) $P_i = -20 \text{ dBm}$
 (4) $P_i = -15 \text{ dBm}$

Fig 14. Input return loss as a function of frequency; typical values



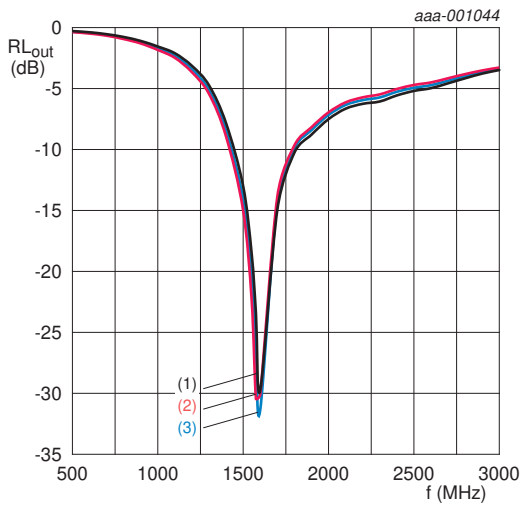
$P_i = -45 \text{ dBm}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}.$
 (1) $V_{CC} = 1.5 \text{ V}$
 (2) $V_{CC} = 1.8 \text{ V}$
 (3) $V_{CC} = 2.2 \text{ V}$

Fig 15. Input return loss as a function of frequency; typical values



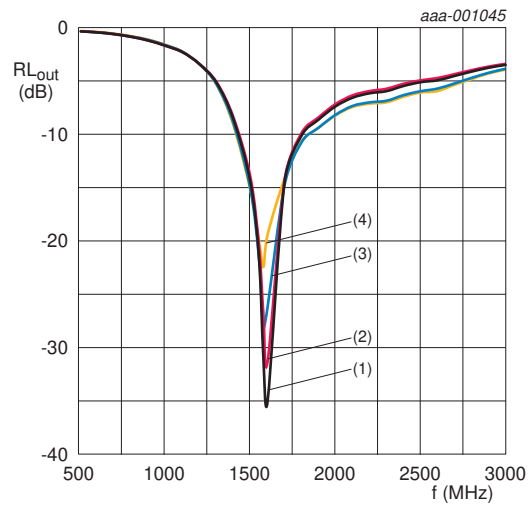
$T_{\text{amb}} = 25 \text{ }^\circ\text{C}; f = 1575 \text{ MHz}.$
 (1) $V_{CC} = 1.5 \text{ V}$
 (2) $V_{CC} = 1.8 \text{ V}$
 (3) $V_{CC} = 2.2 \text{ V}$

Fig 16. Input return loss as a function of input power; typical values



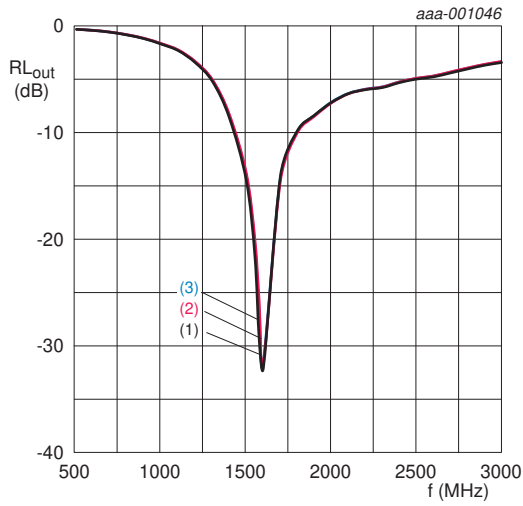
$V_{CC} = 1.8 \text{ V}; P_i = -45 \text{ dBm}.$
 (1) $T_{\text{amb}} = -40 \text{ }^\circ\text{C}$
 (2) $T_{\text{amb}} = +25 \text{ }^\circ\text{C}$
 (3) $T_{\text{amb}} = +85 \text{ }^\circ\text{C}$

Fig 17. Output return loss as a function of frequency; typical values



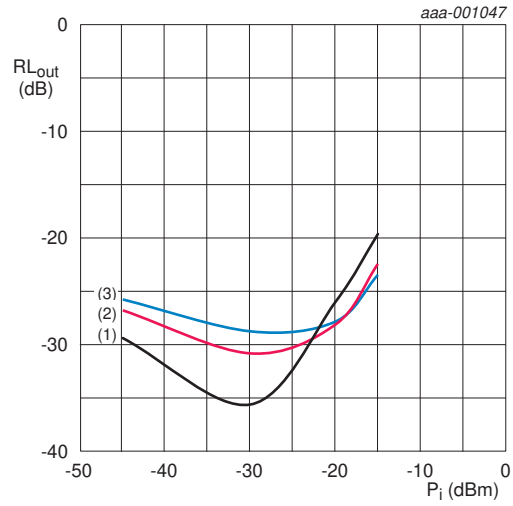
$V_{CC} = 1.8 \text{ V}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}.$
 (1) $P_i = -45 \text{ dBm}$
 (2) $P_i = -30 \text{ dBm}$
 (3) $P_i = -20 \text{ dBm}$
 (4) $P_i = -15 \text{ dBm}$

Fig 18. Output return loss as a function of frequency; typical values



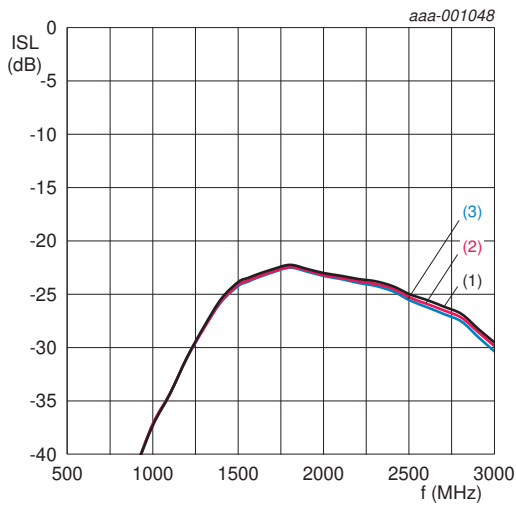
$P_i = -45 \text{ dBm}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$.
 (1) $V_{\text{CC}} = 1.5 \text{ V}$
 (2) $V_{\text{CC}} = 1.8 \text{ V}$
 (3) $V_{\text{CC}} = 2.2 \text{ V}$

Fig 19. Output return loss as a function of frequency; typical values



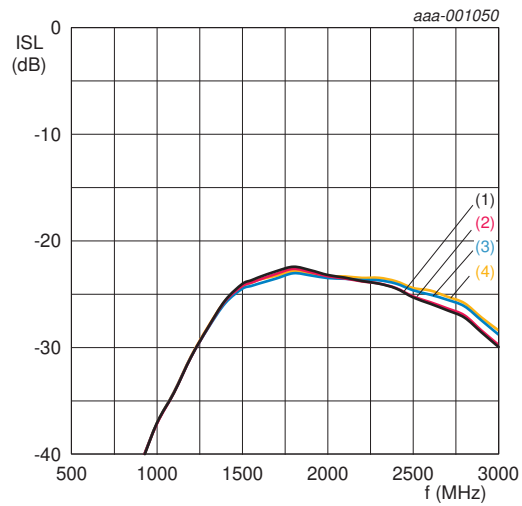
$T_{\text{amb}} = 25 \text{ }^\circ\text{C}$; $f = 1575 \text{ MHz}$.
 (1) $V_{\text{CC}} = 1.5 \text{ V}$
 (2) $V_{\text{CC}} = 1.8 \text{ V}$
 (3) $V_{\text{CC}} = 2.2 \text{ V}$

Fig 20. Output return loss as a function of input power; typical values



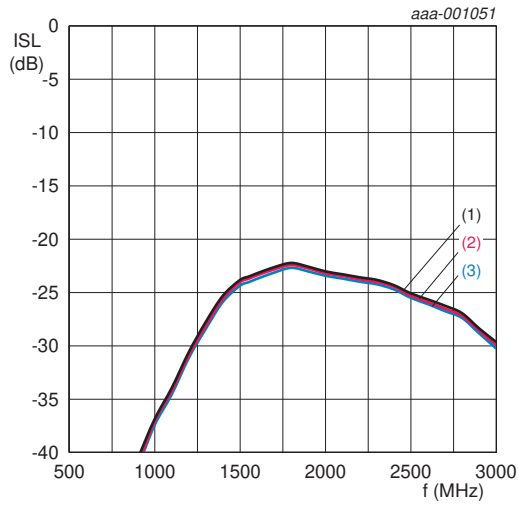
$V_{\text{CC}} = 1.8 \text{ V}$; $P_i = -45 \text{ dBm}$.
 (1) $T_{\text{amb}} = -40 \text{ }^\circ\text{C}$
 (2) $T_{\text{amb}} = +25 \text{ }^\circ\text{C}$
 (3) $T_{\text{amb}} = +85 \text{ }^\circ\text{C}$

Fig 21. Isolation as a function of frequency; typical values



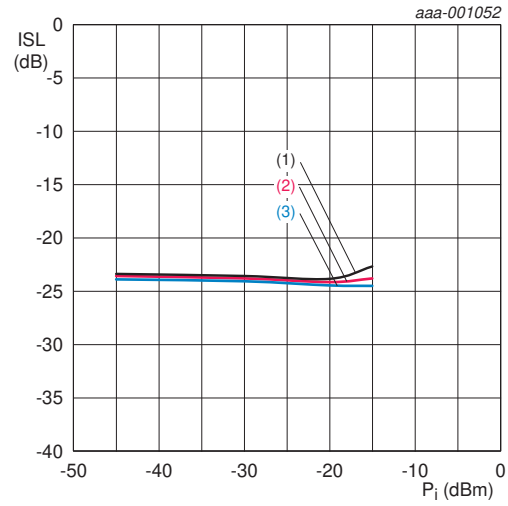
$V_{\text{CC}} = 1.8 \text{ V}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$.
 (1) $P_i = -45 \text{ dBm}$
 (2) $P_i = -30 \text{ dBm}$
 (3) $P_i = -20 \text{ dBm}$
 (4) $P_i = -15 \text{ dBm}$

Fig 22. Isolation as a function of frequency; typical values



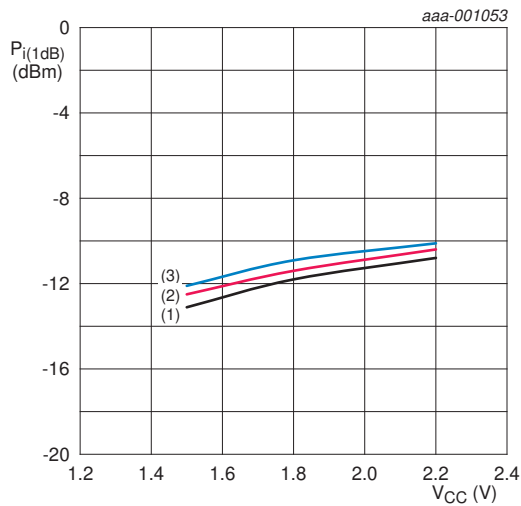
$P_i = -45 \text{ dBm}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$.
 (1) $V_{\text{CC}} = 1.5 \text{ V}$
 (2) $V_{\text{CC}} = 1.8 \text{ V}$
 (3) $V_{\text{CC}} = 2.2 \text{ V}$

Fig 23. Isolation as a function of frequency; typical values



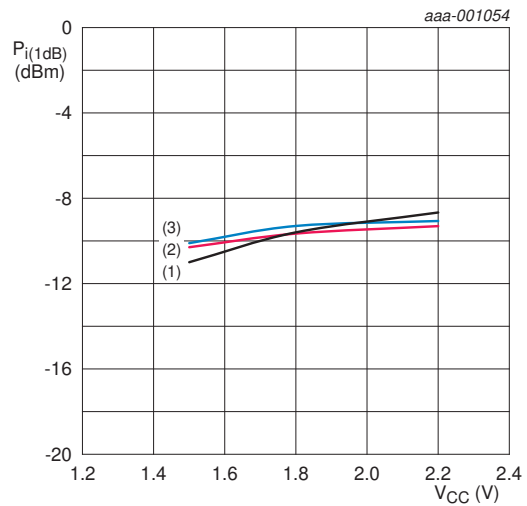
$T_{\text{amb}} = 25 \text{ }^\circ\text{C}$; $f = 1575 \text{ MHz}$.
 (1) $V_{\text{CC}} = 1.5 \text{ V}$
 (2) $V_{\text{CC}} = 1.8 \text{ V}$
 (3) $V_{\text{CC}} = 2.2 \text{ V}$

Fig 24. Isolation as a function of input power; typical values



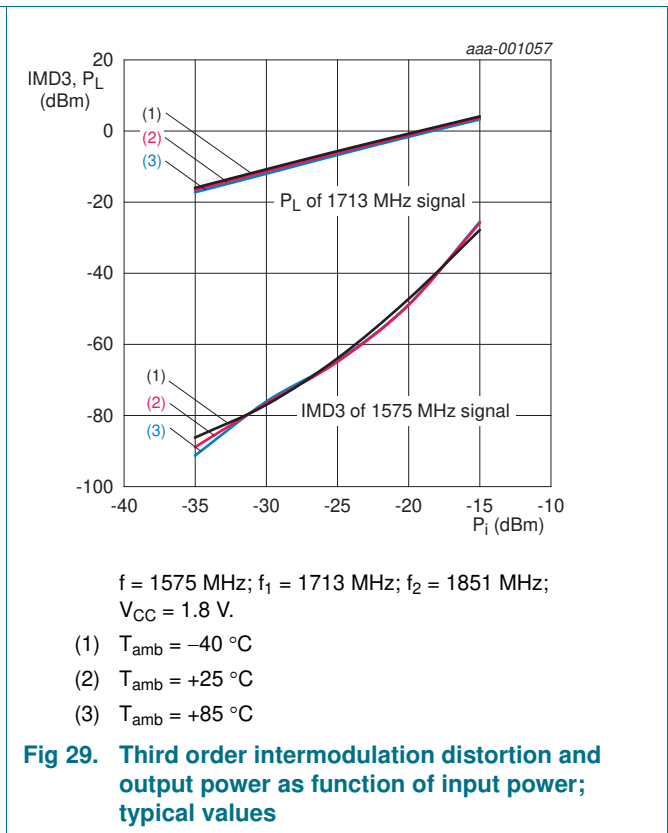
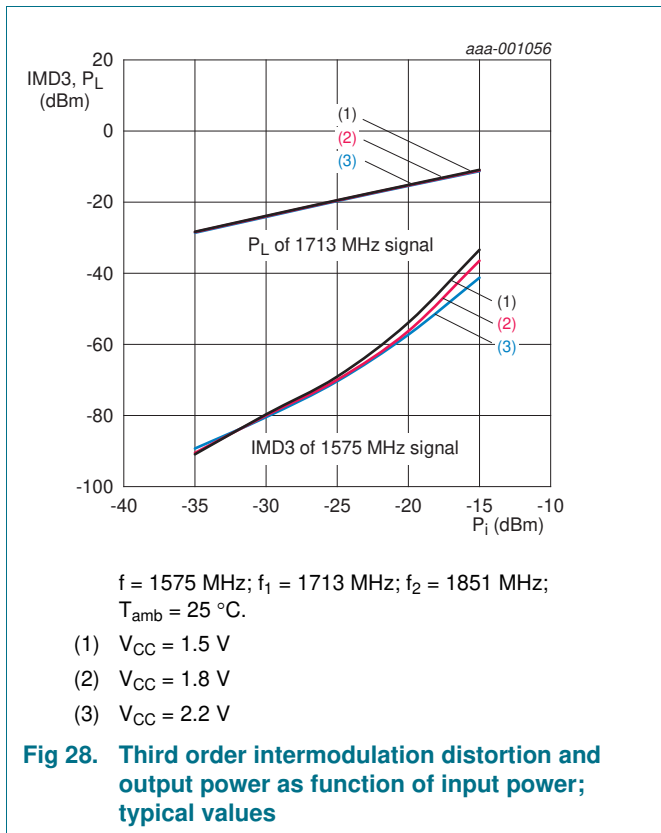
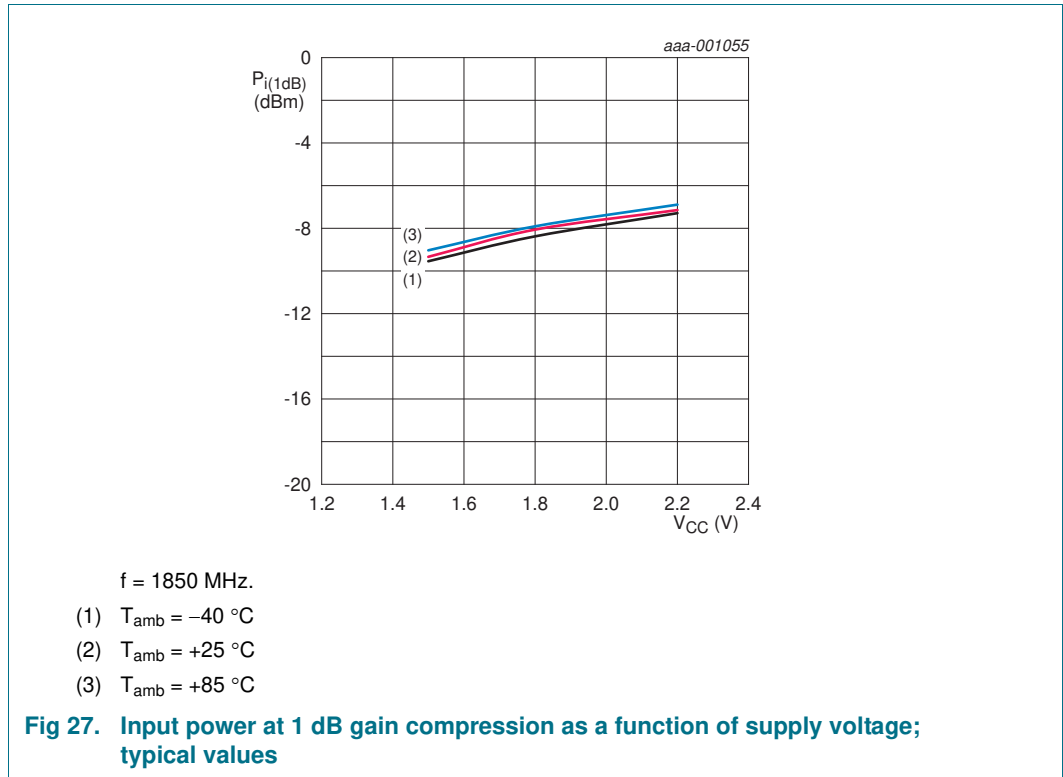
$f = 1575 \text{ MHz}$.
 (1) $T_{\text{amb}} = -40 \text{ }^\circ\text{C}$
 (2) $T_{\text{amb}} = +25 \text{ }^\circ\text{C}$
 (3) $T_{\text{amb}} = +85 \text{ }^\circ\text{C}$

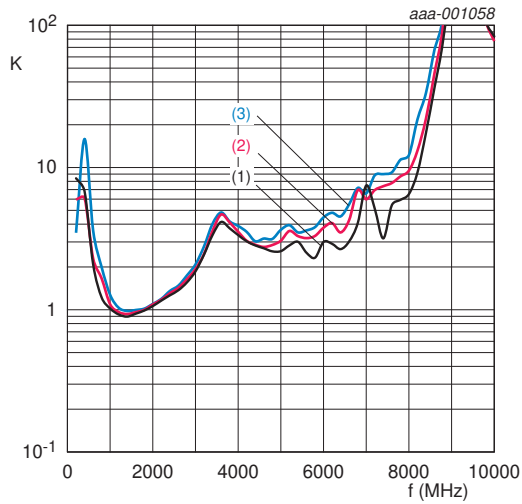
Fig 25. Input power at 1 dB gain compression as a function of supply voltage; typical values



$f = 850 \text{ MHz}$.
 (1) $T_{\text{amb}} = -40 \text{ }^\circ\text{C}$
 (2) $T_{\text{amb}} = +25 \text{ }^\circ\text{C}$
 (3) $T_{\text{amb}} = +85 \text{ }^\circ\text{C}$

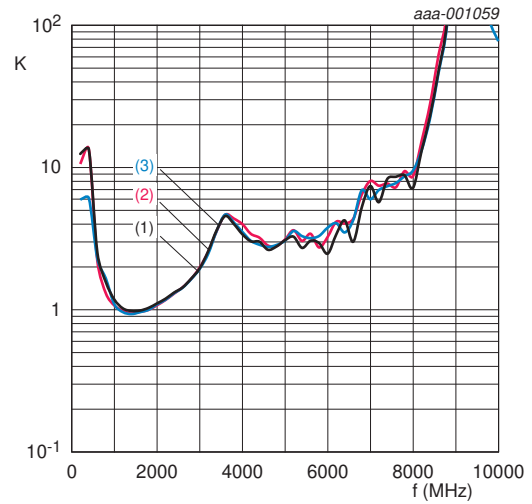
Fig 26. Input power at 1 dB gain compression as a function of supply voltage; typical values





$V_{CC} = 1.8\text{ V}; P_i = -45\text{ dBm}.$
 (1) $T_{amb} = -40\text{ }^\circ\text{C}$
 (2) $T_{amb} = +25\text{ }^\circ\text{C}$
 (3) $T_{amb} = +85\text{ }^\circ\text{C}$

Fig 30. Rollett stability factor as a function of frequency; typical values



$T_{amb} = 25\text{ }^\circ\text{C}; P_i = -45\text{ dBm}.$
 (1) $V_{CC} = 1.5\text{ V}$
 (2) $V_{CC} = 1.8\text{ V}$
 (3) $V_{CC} = 2.2\text{ V}$

Fig 31. Rollett stability factor as a function of frequency; typical values

9. Package outline

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

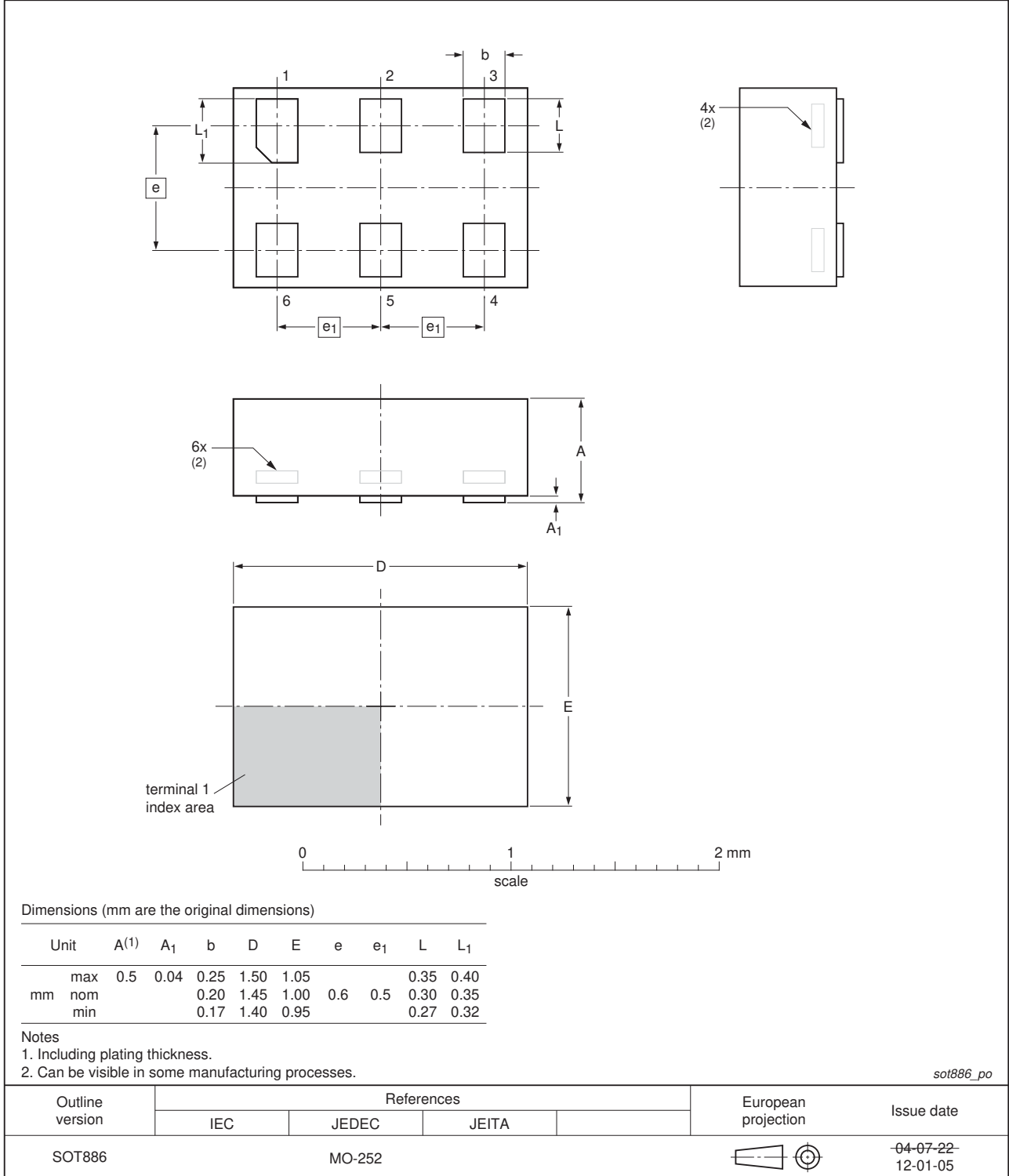


Fig 32. Package outline SOT886 (XSON6)

10. Abbreviations

Table 10. Abbreviations

Acronym	Description
AC	Alternating Current
ATM	Automated Teller Machine (cash dispenser)
DC	Direct Current
GLONASS	GLObal NAVigation Satellite System
GNSS	Global Navigation Satellite System
GPS	Global Positioning System
HBM	Human Body Model
MMIC	Monolithic Microwave Integrated Circuit
PC	Personal Computer
PCB	Printed Circuit Board
RF	Radio Frequency
SiGe:C	Silicon Germanium Carbon

11. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGU8007 v.2	20120330	Product data sheet	-	BGU8007 v.1
Modifications:				
<ul style="list-style-type: none"> • Added 'Compass' to descriptive title • Section 1.3 on page 2: added 'Compass' to text • Section 1.2 on page 1: row 7, changed 2.2 V to 2.5 V • Table 1 on page 2: changed max. value V_{CC} from 2.2 V to 2.5 V • Table 7 on page 4: changed max. value V_{CC} from 2.2 V to 2.5 V • Table 8 on page 5: changed max. value V_{CC} from 2.2 V to 2.5 V • Table 5 on page 3: Several additions and changes 				
BGU8007 v.1	20111011	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 30 March 2012

Document identifier: BGU8007